优尚

YOUSHANG SEMICONDUCTOR

**设计研发新型功率器件**

各类小信号开关

中低压及高压大电流等场效应管

企业微信二维码　　　企业QQ二维码

Features

- Low $R_{DS(ON)}$
    - 72 mΩ @V_{GS} = -4.5V
    - 108 mΩ @V_{GS} = -2.7V
    - 123 mΩ @V_{GS} = -2.5V
- Low Input/Output Leakage

Mechanical Data

- Case: SOT23
- Case Material - Molded Plastic, "Green" Molding Compound. UL Flammability Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020D
- Terminals: Finish - Matte Tin annealed over Copper leadframe. Solderable per MIL-STD-202, Method 208 ⒠③
- Terminal Connections: See Diagram Below
- Weight: 0.008 grams (approximate)

SOT23

Drain

Gate
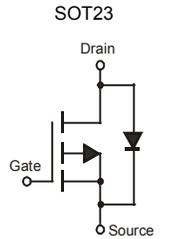
Source

TOP VIEW

Internal Schematic

D

G   S
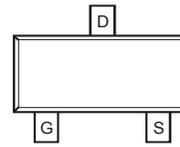
TOP VIEW

Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Characteristic		Symbol	Value	Unit
Drain-Source Voltage		V_{DSS}	-20	V
Gate-Source Voltage		V_{GSS}	±12	V
Drain Current (Note 5) Continuous	T_A = +25°C T_A = +70°C	I_D	-3.0 -2.4	A
Pulsed Drain Current (Note 6)		I_{DM}	-15	A
Body-Diode Continuous Current (Note 5)		I_S	2.0	A

Thermal Characteristics

Characteristic	Symbol	Value	Unit
Total Power Dissipation (Note 5)	P_D	1.4	W
Thermal Resistance, Junction to Ambient (Note 5); Steady-State	$R_{θJA}$	90	°C/W
Operating and Storage Temperature Range	T_J, T_{STG}	-55 to +150	°C

Notes: 5. Device mounted on 1"x1", FR-4 PC board with 2 oz. Copper and test pulse width t ≤10s.
6. Repetitive Rating, pulse width limited by junction temperature.

Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic		Symbol	Min	Typ	Max	Unit	Test Condition
STATIC PARAMETERS							
Drain-Source Breakdown Voltage		BV_{DSS}	-20	—	—	V	I_D = -250µA, V_{GS} = 0V
Zero Gate Voltage Drain Current	T_J = +25°C	I_{DSS}	—	—	-1	µA	V_{DS} = -20V, V_{GS} = 0V
Gate-Body Leakage Current		I_{GSS}	—	—	±100	nA	V_{DS} = 0V, V_{GS} = ±12V
Gate Threshold Voltage		$V_{GS(th)}$	-0.6	—	-1.25	V	V_{DS} = V_{GS}, I_D = -250µA
On State Drain Current (Note 7)		$I_{D (ON)}$	-15	—	—	A	V_{GS} = -4.5V, V_{DS} = -5V
Static Drain-Source On-Resistance (Note 7)		$R_{DS(ON)}$	—	51 87 99	72 108 123	mΩ	V_{GS} = -4.5V, I_D = -3.5A V_{GS} = -2.7V, I_D = -3.0A V_{GS} = -2.5V, I_D = -2.6A
Forward Transconductance (Note 7)		g_{FS}	—	7.3	—	S	V_{DS} = -10V, I_D = -3.0A
Diode Forward Voltage (Note 5)		V_{SD}	—	0.79	-1.26	V	I_S = -1.7A, V_{GS} = 0V
Maximum Body-Diode Continuous Current (Note 5)		I_S	—	—	1.7	A	—
DYNAMIC PARAMETERS (Note 8)							
Total Gate Charge		Q_g	—	7.3	—	nC	V_{GS} = -4.5V, V_{DS} = -10V, I_D = -3.0A
Gate-Source Charge		Q_{gs}	—	2.0	—	nC	V_{GS} = -4.5V, V_{DS} = -10V, I_D = -3.0A
Gate-Drain Charge		Q_{gd}	—	1.9	—	nC	V_{GS} = -4.5V, V_{DS} = -10V, I_D = -3.0A
Turn-On Delay Time		$t_{D(on)}$	—	12	—	ns	V_{DS} = -10V, V_{GS} = -4.5V, R_L = 10Ω, R_G = 6Ω
Turn-On Rise Time		t_r	—	20	—	ns	
Turn-Off Delay Time		$t_{D(off)}$	—	38	—	ns	
Turn-Off Fall Time		t_f	—	41	—	ns	
Input Capacitance		C_{iss}	—	443	—	pF	V_{DS} = -16V, V_{GS} = 0V, f = 1.0MHz
Output Capacitance		C_{oss}	—	128	—	pF	
Reverse Transfer Capacitance		C_{rss}	—	101	—	pF	

Notes: 7. Test pulse width t = 300µs.
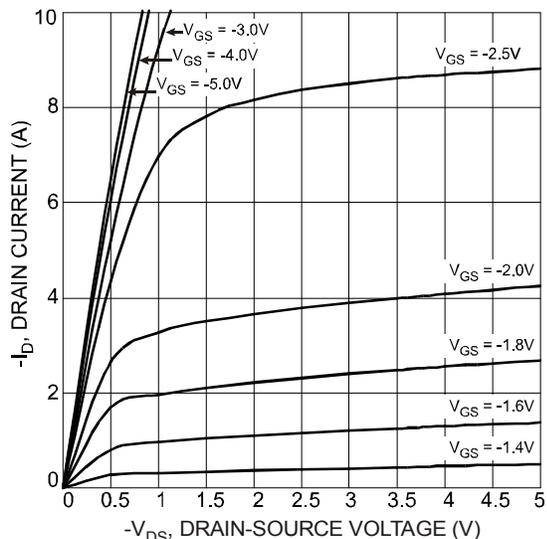8. Guaranteed by design. Not subject to production testing.

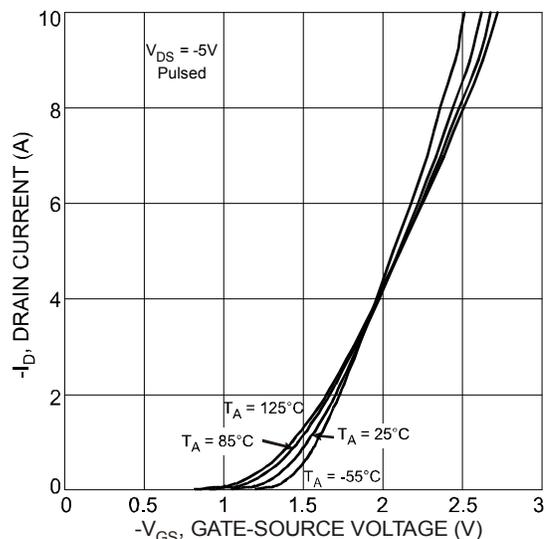Fig. 1 Typical Output Characteristics

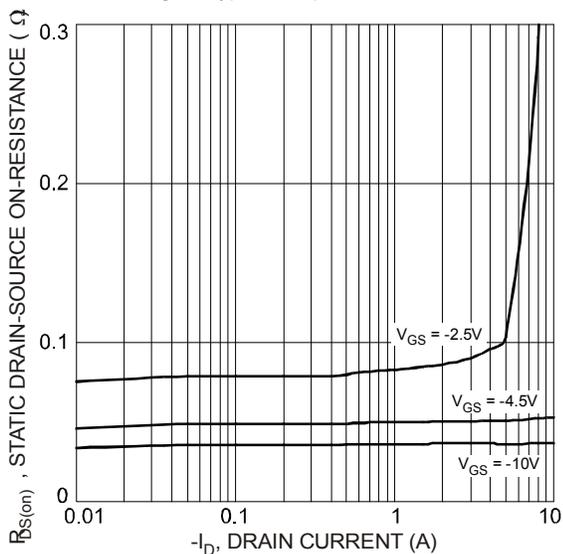Fig. 2 Typical Transfer Characteristics

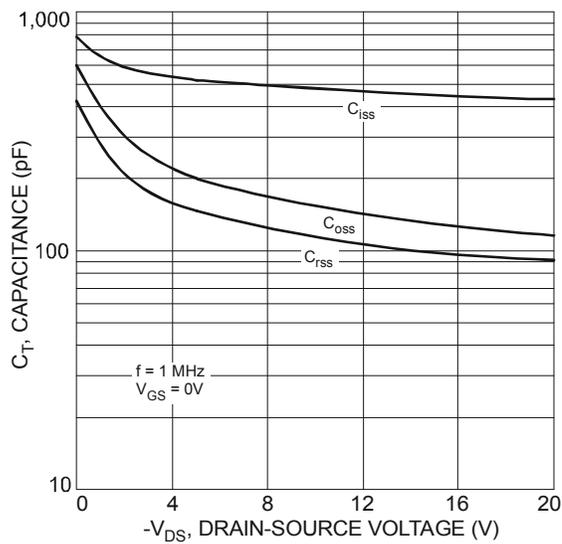Fig. 3 On-Resistance vs. Drain Current and Gate Voltage
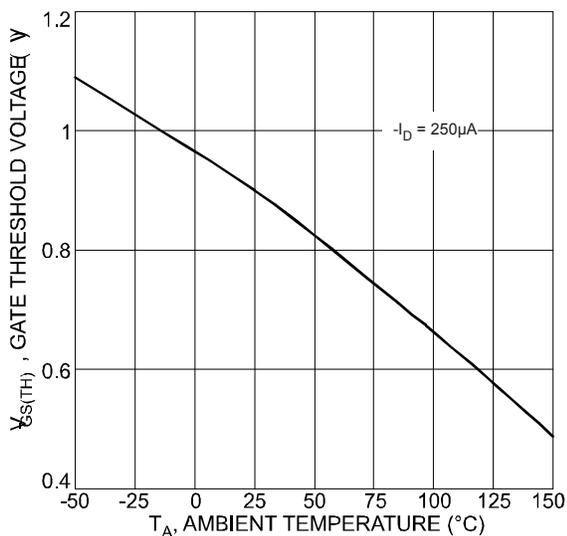

Fig. 4 Typical Total Capacitance

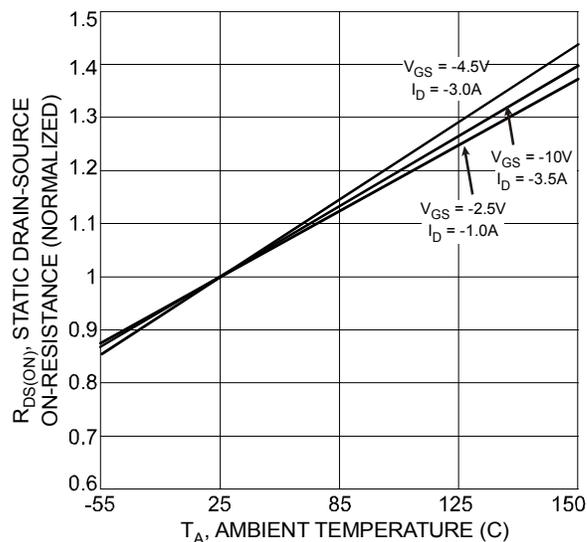Fig. 5 Gate Threshold Voltage vs. Ambient Temperature

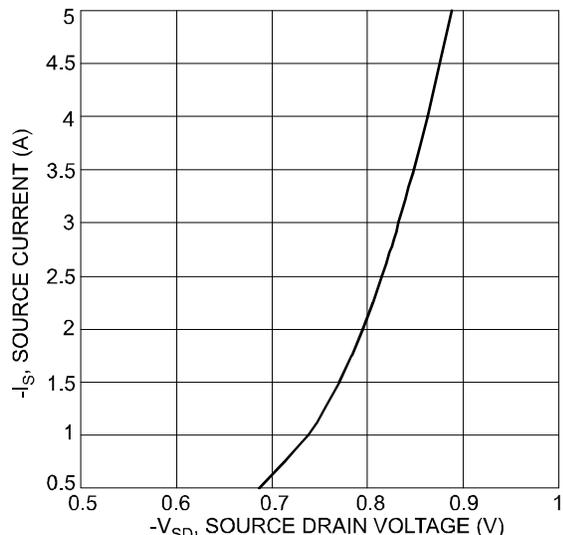Fig. 6 Normalized Static Drain-Source On-Resistance vs. Ambient Temperature

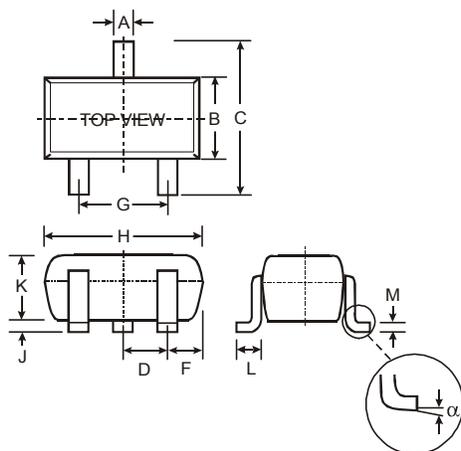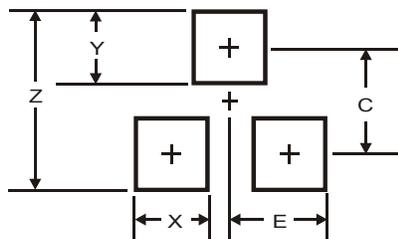Fig. 7 Reverse Drain Current vs. Source-Drain Voltage

Package Outline Dimensions

SOT23		
Dim	Min	Max
A	0.37	0.51
B	1.20	1.40
C	2.30	2.50
D	0.89	1.03
F	0.45	0.60
G	1.78	2.05
H	2.80	3.00
J	0.013	0.10
K	0.903	1.10
L	0.45	0.61
M	0.085	0.180
α	0°	8°
All Dimensions in mm		

Suggested Pad Layout

Dimensions	Value (in mm)
Z	2.9
X	0.8
Y	0.9
C	2.0
E	1.35